Product Change Notification 32959 is complete and has been sent to approved customers. Please e-mail <u>QA_PCN_SUPPORT@micron.com</u> if you have any questions regarding this Product Change Notification.

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eMMC v4.41 Automotive 4GB (J54U) Silicon Improvement, Assembly Site Transfer, 2DID Barcode Addition

PCN: 32959

Published: 2018-10-25

Revision History:

Revision 1, 2018-10-30: This document supersedes the original PCN #32959, dated 2018-10-25. Actual dates reflecting 6 months and 12 months following the original publication date have been provided for "Last Buy and "Last Ship."

Revision 2, 2019-01-11: This document supersedes the original PCN #32959, dated 2018/10/25. Sample and Qual Data Availability dates and also the Last Purchase and Last Shipment dates have been changed.

Туре:	Manufacturing Site – Change or Addition, Product Mark/label Change, Manufacturing Process Change, End of Life
Description:	 Micron is implementing silicon improvement by converting bond pad material for legacy NAND devices, transferring assembly site and adding new top side mark (2DID barcode) for better traceability. The product will be identified by new Marketing Part numbers. Existing part numbers will be discontinued 1. The bond pad metallization will convert from Ni/Pd to Aluminum (AI). The change will not impact the final packaged product. Other DRAM/NAND technologies at FAB6 use the AI bond pad process and is proven to be more robust.

	Was	ls	
	Layers:	Layers:	
	Metal 2: Cu+ Ni/Pd (Plating)	Metal 2: AI (Sputter)	
			1
	2. Assembly site transfer from:		
	Current: Amkor Technology Korea, 957	Daechon-dong, Buk-gu, Gwangju	, Korea
	New: Micron Semiconductor Malaysia Sd 84000, Malaysia	n. Bhd., Tanjung Agas Industrial	Area, Muar, Johor
	 For improved unit-level traceability, 2DID refer to the page 6 of CSN-11: Product Mark marking details. 		
Reason:	Improved Product Quality and Reliability, Manufacturing Efficiency, Supply Flexibility/Security		
Product Affected:	eMMC v4.41 Automotive 4GB (J54U)		
Affected Micron Part Number	Recommended Replacement	Customer Part Number	r
<u>Component</u>			
MTFC4GLGDM-AIT Z	MTFC4GLGDM-AIT A		
MTFC4GLGDQ-AIT Z	MTFC4GLGDQ-AIT A		
MTFC4GLMDQ-AIT Z	MTFC4GLMDQ-AIT A		
	*Materials that have been ordered	are in bold .	
Method of Identification:	New Marketing Part numbers as well as master shipping label will indcate country of orgin from Korea to Malaysia.		
Micron Sites Affected:	MMY - Muar_Malaysia		
Sample Available:	2019-02-04		

Qual Data Available:	2019-02-04
Last Purchase Date*:	2019-06-28
Last Shipment Date:	2019-12-27

*Orders placed prior to the last purchase date are subject to current inventory levels, which may vary based on market conditions and customer demand. Early orders are encouraged. Any products from a previously accepted order that have not shipped as of the last purchase date may be considered non-cancelable/non-returnable at Micron's discretion.

Additionally, Micron may accept orders for products following the last purchase date, subject to current inventory levels, which may vary based on market conditions and customer demand, and such products may be considered non-cancelable/non-returnable at Micron's discretion.

NOTE: Per JEDEC Standard JESD46-C Section 3.2.3; lack of acknowledgment of this PCN within 30 days constitutes acceptance of change.

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